Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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SmartMesh IP Node 2.4GHz 802.15.4e Wireless Mote-on-Chip

NETWORK FEATURES

- Complete Radio Transceiver, Embedded Processor, and Networking Software for Forming a Self-Healing Mesh Network
- SmartMesh® Networks Incorporate:
  - Time Synchronized Network-Wide Scheduling
  - Per Transmission Frequency Hopping
  - Redundant Spatially Diverse Topologies
  - Network-Wide Reliability and Power Optimization
  - NIST Certified Security
- SmartMesh Networks Deliver
  - >99.999% Network Reliability Achieved in the Most Challenging RF Environments
  - Sub 50µA Routing Nodes
- Compliant to 6LoWPAN Internet Protocol (IP) and IEEE 802.15.4e Standards

LTC5800-IPM FEATURES

- Industry-Leading Low Power Radio Technology
  - 4.5mA to Receive a Packet
  - 9.7mA to Transmit at 8dBm
- PCB Module Versions Available (LTP5901/ LTP5902-IPM) with RF Modular Certifications
- 2.4GHz, IEEE 802.15.4e System-on-Chip
- 72-Pin 10mm × 10mm QFN Package
- Micrium µCOS-II Real Time Operating System based On-Chip Software Development Kit

DESCRIPTION

SmartMesh IP™ wireless sensor networks are self managing, low power internet protocol (IP) networks built from wireless nodes called motes. The LTC®5800-IPM is the IP mote product in the Eterna®* family of IEEE 802.15.4e System-on-Chip (SoC) solutions, featuring a highly-integrated, low power radio design by Dust Networks® as well as an ARM Cortex-M3 32-bit microprocessor running Dust's embedded SmartMesh IP networking software.

The LTC5800-IPM SoC features an on-chip power amplifier (PA) and transceiver, requiring only power supply decoupling, crystals, and antenna with matching circuitry to create a complete wireless node.

With Dust's time-synchronized SmartMesh IP networks, all motes in the network may route, source or terminate data, while providing many years of battery powered operation. The SmartMesh IP software provided with the LTC5800-IPM is fully tested and validated, and is readily configured via a software Application Programming Interface.

SmartMesh IP motes deliver a highly flexible network with proven reliability and low power performance in an easy-to-integrate platform.

* Eterna is Dust Networks' low power radio SoC architecture.

TYPICAL APPLICATION

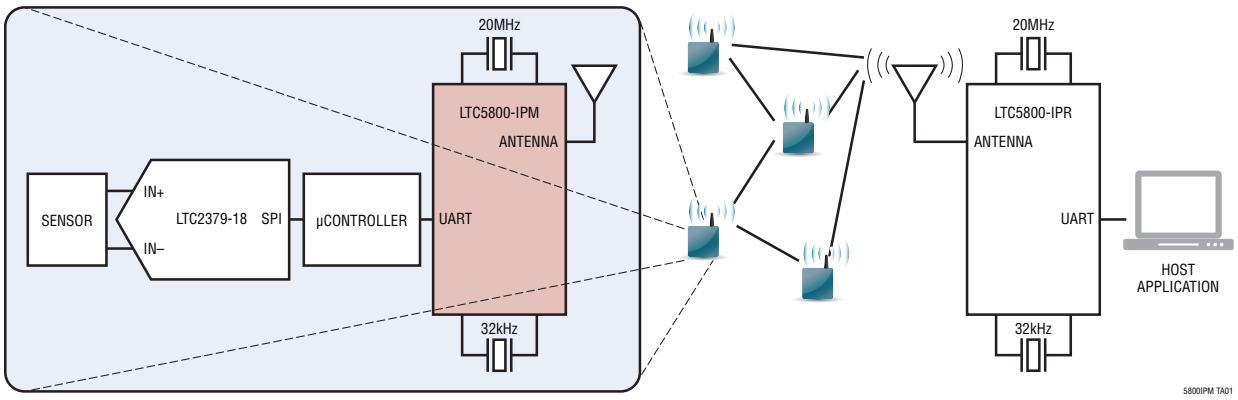


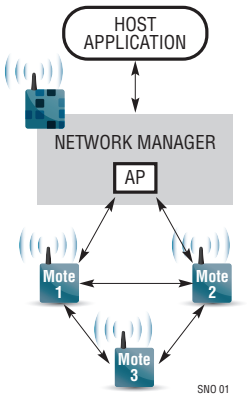
TABLE OF CONTENTS

SMARTMESH NETWORK OVERVIEW

A SmartMesh network consists of a self-forming multi-hop mesh of nodes, known as motes, which collect and relay data, and a network manager that monitors and manages network performance and security, and exchanges data with a host application.

SmartMesh networks communicate using a time slotted channel hopping (TSCH) link layer, pioneered by Dust Networks. In a TSCH network, all motes in the network are synchronized to within less than a millisecond. Time in the network is organized into time slots, which enables collision-free packet exchange and per-transmission channel-hopping. In a SmartMesh network, every device has one or more parents (e.g. mote 3 has motes 1 and 2 as parents) that provide redundant paths to overcome communications interruption due to interference, physical obstruction or multi-path fading. If a packet transmission fails on one path, the next retransmission may try on a different path and different RF channel.

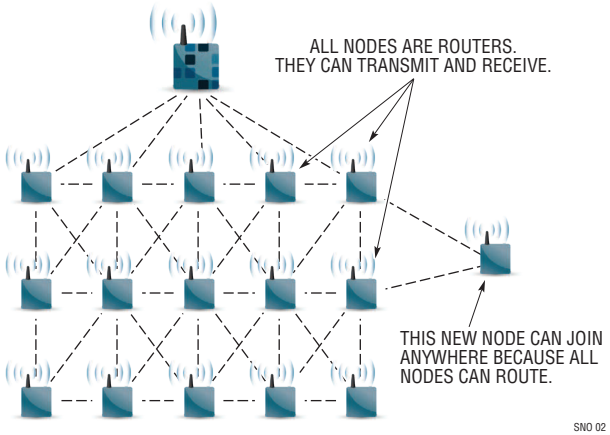
A network begins to form when the network manager instructs its on-board Access Point (AP) radio to begin sending advertisements—packets that contain information that enables a device to synchronize to the network and request to join. This message exchange is part of the security handshake that establishes encrypted communications between the manager or application, and mote. Once motes have joined the network, they maintain synchronization through time corrections when a packet is acknowledged.



An ongoing discovery process ensures that the network continually discovers new paths as the RF conditions change. In addition, each mote in the network tracks performance statistics (e.g. quality of used paths, and lists of potential paths) and periodically sends that information to the network manager in packets called health reports.

The Network Manager uses health reports to continually optimize the network to maintain >99.999% data reliability even in the most challenging RF environments.

The use of TSCH allows SmartMesh devices to sleep in between scheduled communications and draw very little power in this state. Motes are only active in time slots where they are scheduled to transmit or receive, typically resulting in a duty cycle of < 1%. The optimization software in the Network Manager coordinates this schedule automatically. When combined with the Eterna low power radio, every mote in a SmartMesh network—even busy routing ones—can run on batteries for years. By default, all motes in a network are capable of routing traffic from other motes, which simplifies installation by avoiding the complexity of having distinct routers vs non-routing end nodes. Motes may be configured as non-routing to further reduce that particular mote's power consumption and to support a wide variety of network topologies.



At the heart of SmartMesh motes and network managers is the Eterna IEEE 802.15.4e System-on-Chip (SoC), featuring Dust Networks' highly integrated, low power radio design, plus an ARM Cortex-M3 32-bit microprocessor running SmartMesh networking software. The SmartMesh networking software comes fully compiled yet is configurable via a rich set of Application Programming Interfaces (APIs) which allows a host application to interact with the network, e.g. to transfer information to a device, to configure data publishing rates on one or more motes, or to monitor network state or performance metrics. Data publishing can be uniform or different for each device, with motes being able to publish infrequently or faster than once per second as needed.

ABSOLUTE MAXIMUM RATINGS

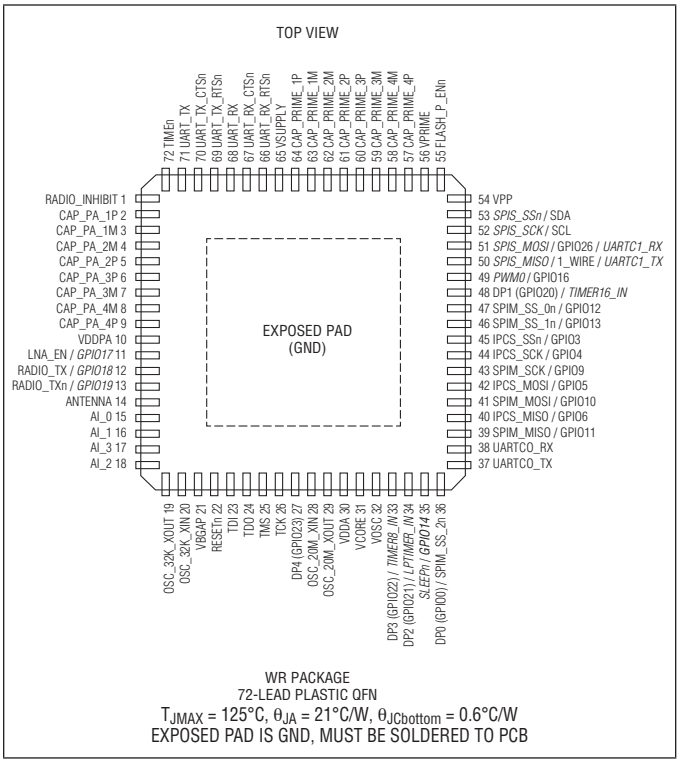
(Note 1)

Supply Voltage on VSUPPLY 4.20V
Input Voltage on AI_0/1/2/3 Inputs 1.80V
Voltage on Any Digital I/O Pin ...–0.3V to V_{SUPPLY} + 0.3V
Input RF Level 10dBm
Storage Temperature Range (Note 3) ..... –55°C to 125°C
Junction Temperature (Note 3) ..... 125°C
Operating Temperature Range
LTC5800I ..... –40°C to 85°C
LTC5800H ..... –55°C to 105°C

CAUTION: This part is sensitive to electrostatic discharge (ESD). It is very important that proper ESD precautions be observed when handling the LTC5800-IPM.

PIN CONFIGURATION

Pin functions shown in italics are currently not supported in software.



WR PACKAGE
72-LEAD PLASTIC QFN
T_{JMAX} = 125°C, θ_{JA} = 21°C/W, $\theta_{JCbottom}$ = 0.6°C/W
EXPOSED PAD IS GND, MUST BE SOLDERED TO PCB

ORDER INFORMATION

LEAD FREE FINISH	TAPE AND REEL	PART MARKING*	PACKAGE DESCRIPTION	TEMPERATURE RANGE
LTC5800IWR-IPMA#PBF	LTC5800IWR-IPMA#PBF	LTC5800WR-IPMA	72-Lead (10mm × 10mm × 0.85mm) Plastic QFN	–40°C to 85°C
LTC5800HWR-IPMA#PBF	LTC5800HWR-IPMA#PBF	LTC5800WR-IPMA	72-Lead (10mm × 10mm × 0.85mm) Plastic QFN	–55°C to 105°C

*The temperature grade is identified by a label on the shipping container.

For more information on lead free part marking, go to: http://www.linear.com/leadfree/
This product is only offered in trays. For more information go to: http://www.linear.com/packaging/. Some packages are available in 500 unit reels through designated sales channels with #TRMPBF suffix.

RECOMMENDED OPERATING CONDITIONS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
V_{SUPPLY}	Supply Voltage	Including Noise and Load Regulation	●	2.1		3.76	V
	Supply Noise	Requires Recommended RLC Filter, 50Hz to 2MHz	●			250	mV
	Operating Relative Humidity	Non-condensing	●	10		90	% RH
	Temperature Ramp Rate	While Operating in Network	●	–8		+8	°C/min

DC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted.

OPERATION/STATE	CONDITIONS		MIN	TYP	MAX	UNITS
Reset	After Power-on Reset			1.2		µA
Power-on Reset	During Power-on Reset, Maximum 750µs + VSUPPLY Rise Time from 1V to 1.9V			12		mA
Doze	RAM on, ARM Cortex-M3, Flash, Radio, and Peripherals Off, All Data and State Retained, 32.768kHz Reference Active			1.2		µA
Deep Sleep	RAM on, ARM Cortex-M3, Flash, Radio, and Peripherals Off, All Data and State Retained, 32.768kHz Reference Inactive			0.8		µA
In-Circuit Programming	RESETn and FLASH_P_ENn Asserted, IPCS_SCK @ 8MHz			20		mA
Peak Operating Current +8dBm +0dBm	System Operating at 14.7MHz, Radio Transmitting, During Flash Write. Maximum duration 4.33 ms.			 30 26		 mA mA
Active	ARM Cortex M3, RAM and Flash Operating, Radio and All Other Peripherals Off. Clock Frequency of CPU and Peripherals Set to 7.3728MHz, VCORE = 1.2V			1.3		mA
Flash Write	Single Bank Flash Write			3.7		mA
Flash Erase	Single Bank Page or Mass Erase			2.5		mA
Radio Tx +0dBm (LTC5800I) +0dBm (LTC5800H) +8dBm (LTC5800I) +8dBm (LTC5800H)	Current With Autonomous MAC Managing Radio Operation, CPU Inactive. Clock Frequency of CPU and Peripherals Set to 7.3728MHz.			 5.4 5.6 9.7 9.9		 mA mA mA mA
Radio Rx LTC5800I LTC5800H	Current With Autonomous MAC Managing Radio Operation, CPU Inactive. Clock Frequency of CPU and Peripherals Set to 7.3728MHz.			 4.5 4.7		 mA mA

RADIO SPECIFICATIONS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted.

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Frequency Band		●	2.4000		2.4835	GHz
Number of Channels		●		15		
Channel Separation		●		5		MHz
Channel Center Frequency	Where k = 11 to 25, as Defined by IEEE.802.15.4	●		2405 + 5•(k-11)		MHz
Raw Data Rate		●		250		kbps
Antenna Pin ESD Protection	HBM Per JEDEC JESD22-A114F			±1000		V
Range (Note 4) Indoor Outdoor Free Space	25°C, 50% RH, +2dBi Omni-Directional Antenna, Antenna 2m Above Ground			 100 300 1200		 m m m

RADIO RECEIVER CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Receiver Sensitivity	Packet Error Rate (PER) = 1% (Note 5)		–93		dBm
Receiver Sensitivity	PER = 50%		–95		dBm
Saturation	Maximum Input Level the Receiver Will Properly Receive Packets		0		dBm
Adjacent Channel Rejection (High Side)	Desired Signal at -82dBm, Adjacent Modulated Channel 5MHz Above the Desired Signal, PER = 1% (Note 5)		22		dBc
Adjacent Channel Rejection (Low Side)	Desired Signal at –82dBm, Adjacent Modulated Channel 5MHz Below the Desired Signal, PER = 1% (Note 5)		19		dBc
Alternate Channel Rejection (High Side)	Desired Signal at –82dBm, Alternate Modulated Channel 10MHz Above the Desired Signal, PER = 1% (Note 5)		40		dBc
Alternate Channel Rejection (Low Side)	Desired Signal at –82dBm, Alternate Modulated Channel 10MHz Below the Desired Signal, PER = 1% (Note 5)		36		dBc
Second Alternate Channel Rejection	Desired Signal at –82dBm, Second Alternate Modulated Channel Either 15MHz Above or Below, PER = 1% (Note 5)		42		dBc
Co-Channel Rejection	Desired Signal at –82dBm, Undesired Signal is an 802.15.4 Modulated Signal at the Same Frequency, PER = 1%		–6		dBc
LO Feed Through			–55		dBm
Frequency Error Tolerance (Note 6)			±50		ppm
Symbol Error Tolerance			±50		ppm
Received Signal Strength Indicator (RSSI) Input Range			–90 to –10		dBm
RSSI Accuracy			±6		dB
RSSI Resolution			1		dB

RADIO TRANSMITTER CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Output Power	Delivered to a 50Ω load				
High Calibrated Setting			8		dBm
Low Calibrated Setting			0		dBm
Spurious Emissions	Conducted Measurement with a 50Ω Single-Ended Load, +8dBm Output Power. All Measurements Made with Max Hold. RF Implementation Per Eterna Reference Design				
30MHz to 1000MHz	R_{BW} = 120kHz, V_{BW} = 100Hz		<–70		dBm
1GHz to 12.75GHz	R_{BW} = 1MHz, V_{BW} = 3MHz		–45		dBm
2.4GHz ISM Upper Band Edge (Peak)	R_{BW} = 1MHz, V_{BW} = 3MHz		–37		dBm
2.4GHz ISM Upper Band Edge (Average)	R_{BW} = 1MHz, V_{BW} = 10Hz		–49		dBm
2.4GHz ISM Lower Band Edge	R_{BW} = 100kHz, V_{BW} = 100kHz		–45		dBc
Harmonic Emissions	Conducted Measurement Delivered to a 50Ω Load, Resolution Bandwidth = 1MHz, Video Bandwidth = 1MHz, RF Implementation Per Eterna Reference Design				
2nd Harmonic			–50		dBm
3rd Harmonic			–45		dBm

DIGITAL I/O CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS (Note 7)		MIN	TYP	MAX	UNITS
V_{IL}	Low Level Input Voltage		●	–0.3		0.6	V
V_{IH}	High Level Input Voltage	(Note 8)	●	VSUPPLY – 0.3		VSUPPLY + 0.3	V
V_{OL}	Low Level Output Voltage	Type 1, $I_{OL(MAX)}$ = 1.2mA	●			0.4	V
	Low Level Output Voltage	Type 2, Low Drive, $I_{OL(MAX)}$ = 2.2mA	●			0.4	V
	Low Level Output Voltage	Type 2, High Drive, $I_{OL(MAX)}$ = 4.5mA	●			0.4	V
V_{OH}	High Level Output Voltage	Type 1, $I_{OH(MAX)}$ = –0.8mA	●	VSUPPLY – 0.3		VSUPPLY + 0.3	V
	High Level Output Voltage	Type 2, Low Drive, $I_{OH(MAX)}$ = –1.6mA	●	VSUPPLY – 0.3		VSUPPLY + 0.3	V
	High Level Output Voltage	Type 2, High Drive, $I_{OH(MAX)}$ = –3.2mA	●	VSUPPLY – 0.3		VSUPPLY + 0.3	V
	Input Leakage Current	Input Driven to VSUPPLY or GND			50		nA
	Pull-Up/Pull-Down Resistance				50		kΩ

TEMPERATURE SENSOR CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted.

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Offset	Temperature Offset Error at 25°C			±0.25		°C
Slope Error				±0.033		°C/°C

ANALOG INPUT CHAIN CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
	Variable Gain Amplifier						
	Gain			1		8	
	Gain Error					2	%
	Offset-Digital to Analog Converter (DAC)						
	Full-Scale				1.80		V
	Resolution				4		Bits
DNL	Differential Non-Linearity					2.7	mV
	Analog to Digital Converter (ADC)						
	Full-Scale, Signal				1.80		V
	Resolution				1.8		mV
	Offset	Mid-Scale			1.4	12	LSB
DNL	Differential Non-Linearity					1	LSB
INL	Integral Non-Linearity					1	LSB
	Settling Time	10kΩ Source Impedance				10	µs
	Conversion Time					20	µs
	Current Consumption				40		µA
	Analog Inputs (Note 8)						
	Load				20		pF
	Series Input Resistance				1		kΩ

SYSTEM CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
	Doze to Active State Transition				5		µs
	Doze to Radio Tx or Rx				1.2		ms
Q_{CCA}	Charge to Sample RF Channel RSSI	Charge Consumed Starting from Doze State and Completing an RSSI Measurement			4		µC
Q_{MAX}	Largest Atomic Charge Operation	Flash Erase, 21ms Max Duration	●			200	µC
	RESETn Pulse Width		●	125			µs

UART AC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
	Permitted R_X Baud Rate Error	Both Application Programming Interface (API) and Command Line Interface (CLI) UARTs	●	–2		2	%
	Generated T_X Baud Rate Error	Both API and CLI UARTs	●	–1		1	%
$t_{RX\_RTS\ to\ RX\_CTS}$	Assertion of UART_RX_RTSn to Assertion of UART_RX_CTSn, or Negation of UART_RX_RTSn to Negation of UART_RX_CTSn		●	0		2	ms
$t_{RX\_CTS\ to\ RX}$	Assertion of UART_RX_CTSn to Start of Byte		●	0		20	ms
$t_{EOP\ to\ RX\_RTS}$	End of Packet (End of the Last Stop Bit) to Negation of UART_RX_RTSn		●	0		22	ms
$t_{BEG\_TX\_RTS\ to\ TX\_CTS}$	Assertion of UART_TX_RTSn to Assertion of UART_TX_CTSn		●	0		22	ms
$t_{END\_TX\_RTS\ to\ TX\_CTS}$	Negation of UART_TX_RTSn to Negation of UART_TX_CTSn	Mode 2 Only				22	ms
$t_{END\_TX\_CTS\ to\ TX\_RTS}$	Negation of UART_TX_CTSn to Negation of UART_TX_RTSn	Mode 4 Only		2			Bit Period
$t_{TX\_CTS\ to\ TX}$	Assertion of UART_TX_CTSn to Start of Byte		●	0		2	Bit Period
$t_{EOP\ to\ TX\_RTS}$	End of Packet (End of the Last Stop Bit) to Negation of UART_TX_RTSn		●	0		1	Bit Period
$t_{RX\_INTERBYTE}$	Receive Inter-Byte Delay		●			100	ms
$t_{RX\_INTERPACKET}$	Receive Inter-Packet Delay		●	20			ms
$t_{TX\_INTERPACKET}$	Transmit Inter-Packet Delay		●	1			Bit Period
$t_{TX\ to\ TX\_CTS}$	Start of Byte to Negation of UART_TX_CTSn		●	0			ns

UART AC CHARACTERISTICS

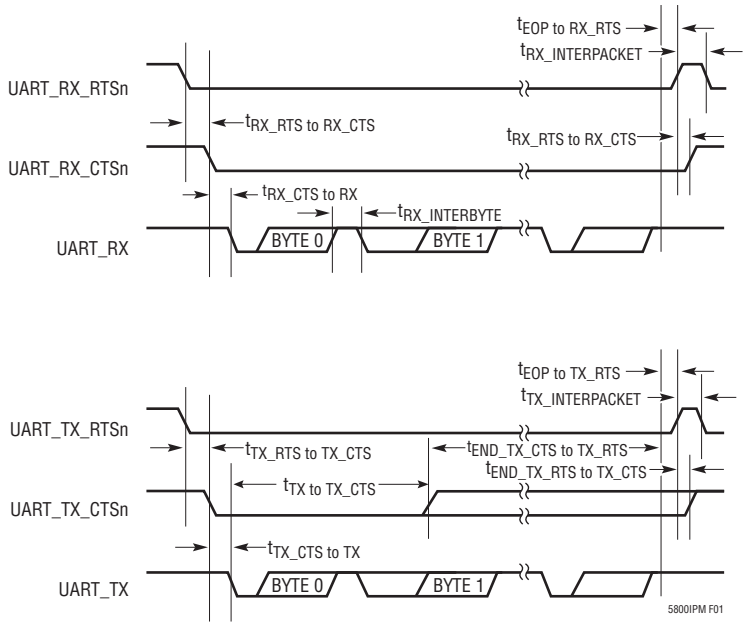


Figure 1. API UART Timing

TIMEn AC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
t_{STROBE}	TIMEn Signal Strobe Width		●	125			µs
$t_{RESPONSE}$	Delay from Rising Edge of TIMEn to the Start of Time Packet on API UART		●	0		100	ms
t_{TIME_HOLD}	Delay from End of Time Packet on API UART to Falling Edge of Subsequent TIMEn		●	0			ns
	Timestamp Resolution (Note 10)		●		1		µs
	Network-Wide Time Accuracy (Note 11)		●		±5		µs

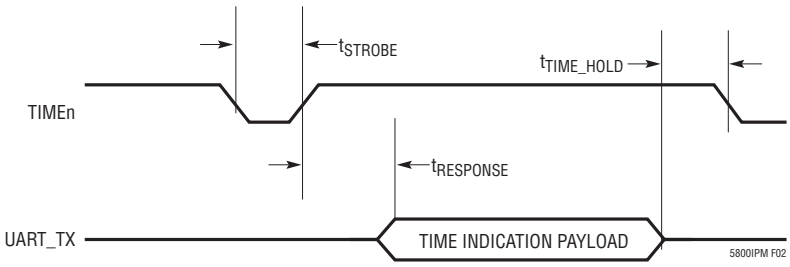


Figure 2. Timestamp Timing

RADIO_INHIBIT AC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
t_{RADIO_OFF}	Delay from Rising Edge of RADIO_INHIBIT to Radio Disabled		●			20	ms
$t_{RADIO\_INHIBIT\_STROBE}$	Maximum RADIO_INHIBIT Strobe Width		●			2	s

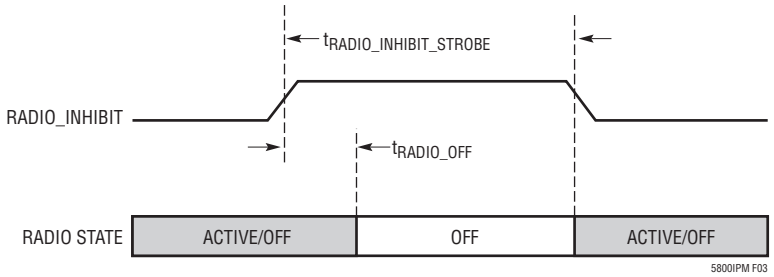


Figure 3. RADIO_INHIBIT Timing

FLASH AC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
t_{WRITE}	Time to Write a 32-Bit Word (Note 12)		●			21	µs
t_{PAGE_ERASE}	Time to Erase a 2kB Page (Note 12)		●			21	ms
t_{MASS_ERASE}	Time to Erase 256kB Flash Bank (Note 12)		●			21	ms
	Data Retention	25°C 85°C 105°C		100 20 8			Years Years Years

FLASH SPI SLAVE AC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
$t_{FP\_EN\_to\_RESET}$	Setup from Assertion of FLASH_P_ENn to Assertion of RESETn		●	0			ns
t_{FP_ENTER}	Delay from the Assertion RESETn to the First Falling Edge of IPCS_SSn		●	125			µs
t_{FP_EXIT}	Delay from the Completion of the Last Flash SPI Slave Transaction to the Negation of RESETn and FLASH_P_ENn (Note 13)		●	10			µs
t_{SSS}	IPCS_SSn Setup to the Leading Edge of IPCS_SCK		●	15			ns
t_{SSH}	IPCS_SSn Hold from Trailing Edge of IPCS_SCK		●	15			ns
t_{CK}	IPCS_SCK Period		●	300			ns
t_{DIS}	IPCS_MOSI Data Setup		●	15			ns
t_{DIH}	IPCS_MOSI Data Hold		●	5			ns
t_{DOV}	IPCS_MISO Data Valid		●	–5		30	ns
t_{OFF}	IPCS_MISO Data Tri-State from Trailing Edge of IPCS_SSn		●	0		30	ns

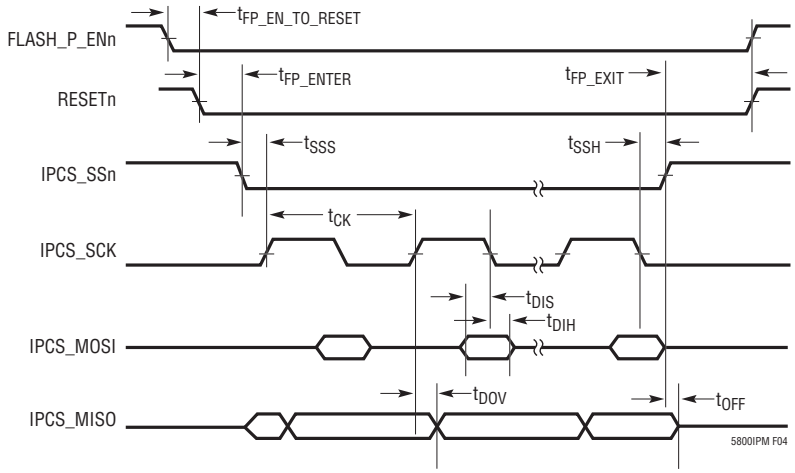


Figure 4. Flash Programming Interface Timing

SPI MASTER AC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
t_{SSS}	SPIM_SSXn Setup to the Leading Edge of SPIM_SCK		●	t_{CK-30}			ns
t_{SSH}	SPIM_SSXn Hold from Trailing Edge of SPIM_SCK		●	t_{CK-30}			ns
t_{CK}	SPIM_SCK Period		●	268			ns
t_{DIS}	SPIM_MOSI Data Setup		●	30			ns
t_{DIH}	SPIM_MOSI Data Hold		●	5			ns
t_{DOV}	SPIM_MISO Data Valid		●	-5		30	ns
t_{OFF}	SPIM_MISO Data Tri-State from Trailing Edge of SPIM_SSXn		●	0		30	ns

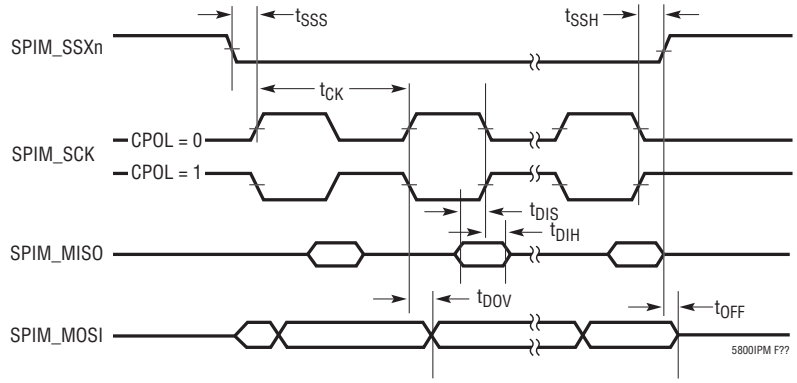


Figure 5. SPI Master Timing - CPHA = 0

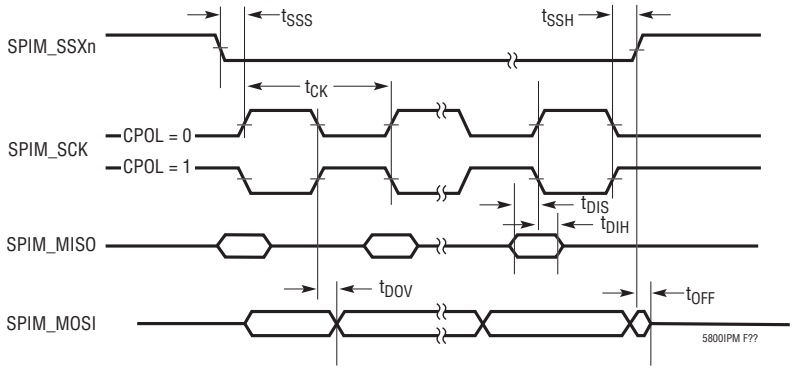


Figure 6. SPI Master Timing - CPHA = 1

I²C AC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
f_{SCL}	SCL Frequency	184kHz Operation 92kHz Operation	●		184.3 92.2	188 94	kHz
t_{HD_STA}	Start Hold Time (SCL from SDA)	184kHz Operation 92kHz Operation	●	1 2			µs
t_{SU_STA}	Setup Time for a Repeated Start	184kHz Operation, 750ns SCL Rise Time 92kHz Operation, 1.5µs SCL Rise Time	●	300 600			ns
t_{HD_DAT}	Data Hold Time	184kHz Operation 92kHz Operation	●	1 2			µs
t_{SU_DAT}	Data Setup Time	184kHz Operation 92kHz Operation	●	1 2			µs
t_{SU_STO}	Setup Time for Stop Condition	184kHz Operation 92kHz Operation	●	1 2			µs

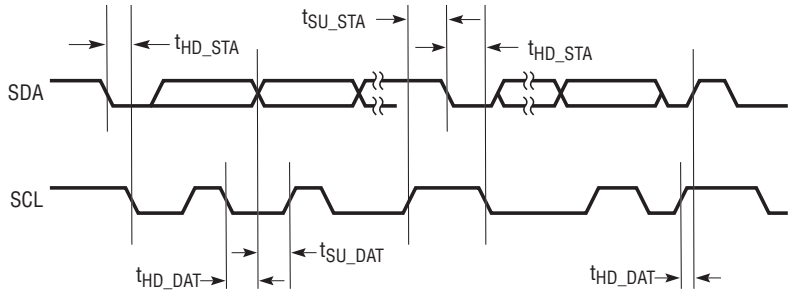


Figure 7. I²C Master Timing

1-WIRE MASTER

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at T_A = 25°C and V_{SUPPLY} = 3.6V unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
t_{RSTL}	Reset Low		●	527	556	584	µs
t_{PS}	Presense Sample		●	60.1	69.4	79	µs
t_{BIT_PERIOD}	1_WIRE Data Bit Period		●	82	86.8	92	µs
t_{LOW0}	1_WIRE Write Data 0 Low Width		●	65	69	82	µs
t_{LOW1}	1_WIRE Write Data 1 Low Width		●	8.2	8.7	9.2	µs
t_{LOWR}	1_WIRE Read Data Low Width		●	8.2	8.7	9.2	µs
t_{RS}	Read Sample from 1_WIRE Low		●	13.2	14.6	15.0	µs

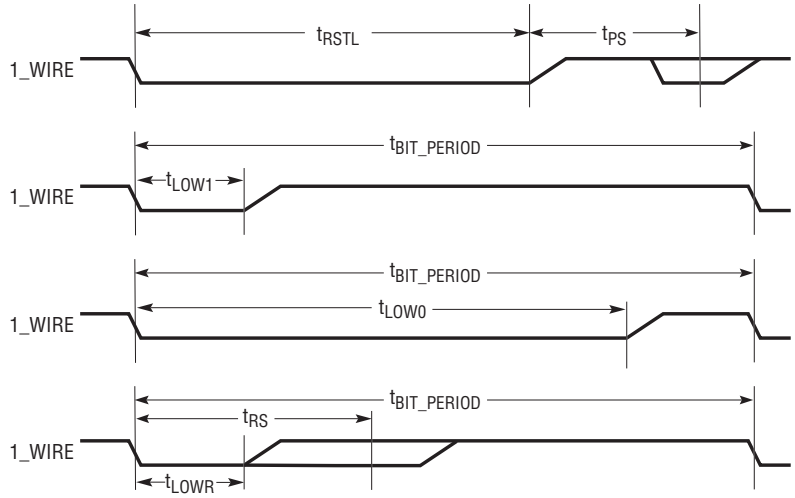


Figure 8. 1-Wire Master Timing

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Note 2: ESD (electrostatic discharge) sensitive device. ESD protection devices are used extensively internal to Eterna. However, high electrostatic discharge can damage or degrade the device. Use proper ESD handling precautions.

Note 3: Extended storage at high temperature is discouraged, as this negatively affects the data retention of Eterna's calibration data. See the FLASH Data Retention section for details.

Note 4: Actual RF range is subject to a number of installation-specific variables including, but not restricted to ambient temperature, relative humidity, presence of active interference sources, line-of-sight obstacles, and near-presence of objects (for example, trees, walls, signage, and so on) that may induce multipath fading. As a result, range varies.

Note 5: As Specified by IEEE Std. 802.15.4-2006: Wireless Medium Access Control (MAC) and Physical Layer (PHY) Specifications for Low-Rate Wireless Personal Area Networks (LR-WPANs) http://standards.ieee.org/findstds/standard/802.15.4-2011.html

Note 6: IEEE Std. 802.15.4-2006 requires transmitters to maintain a frequency tolerance of better than ±40 ppm.

Note 7: Per pin IO types are provided in the Pin Functions section.

Note 8: VIH maximum voltage input must respect the V_{SUPPLY} maximum voltage specification.

Note 9: The analog inputs to the ADC can be modeled as a series resistor to a capacitor. At a minimum the entire circuit, including the source impedance for the signal driving the analog input should be designed to settle to within ¼ LSB within the sampling window to match the performance of the ADC.

Note 10: See the SmartMesh IP Mote API Guide for the timeIndication notification definition.

Note 11: Network time accuracy is a statistical measure and varies over the temperature range, reporting rate and the location of the device relative to the manager in the network. See the Typical Performance Characteristics section for a more detailed description.

Note 12: Code execution from flash banks being written or erased is suspended until completion of the flash operation.

Note 13: Guaranteed by design. Not production tested.

TYPICAL PERFORMANCE CHARACTERISTICS

Network motes typically route through at least two parents the traffic destined for the manager. The supply current graphs shown in Figure 9 include a parameter called descendants. In these graphs the term descendants is short for traffic-weighted descendants and refers to an amount of activity equivalent to the number of descendants if all of the network traffic directed to the mote in question. Generally the number of descendants of a parent is more, typically 2x or more, than the number of traffic-weighted descendants. For example, with reference to Figure 10 mote P1 has 0.75 traffic-weighted descendants. To obtain this value notice that mote D1 routes half its packets through mote P1 adding 0.5 to the traffic-weighted descendant value; the other half of D1's traffic is routed through its other parent, P2. Mote D2 routes half its packets through mote D1 (the other half going through parent P3), which we know routes half its packets to mote P1, adding another 0.25 to the traffic-weighted descendant value for a total traffic-weighted descendant value of 0.75.

As described in the Application Time Synchronization section, Eterna provides two mechanisms for applications to maintain a time base across a network. The synchronization performance plots that follow were generated using the more precise TIMEn input. Publishing rate is the rate a mote application sends upstream data. Synchronization improves as the publishing rate increases. Baseline synchronization performance is provided for a network operating with a publishing rate of zero. Actual performance for applications in network will improve as publishing rates increase. All synchronization testing was performed with the 1-hop mote inside a temperature chamber. Timing errors due to temperature changes and temperature differences both between the manager and this mote and between this mote and its descendents therefore propagated down through the network. The synchronization of the 3-hop and 5-hop motes to the manager was then affected by the temperature ramps even though they were at room temperature. For 2°C/minute testing the temperature chamber was cycled between –40°C and 85°C at this rate for 24 hours. For 8°C/minute testing, the temperature chamber was rapidly cycled between 85°C and 45°C for 8 hours, followed by rapid cycling between –5°C and 45°C for 8 hours, and lastly, rapid cycling between –40°C and 15°C for 8 hours.

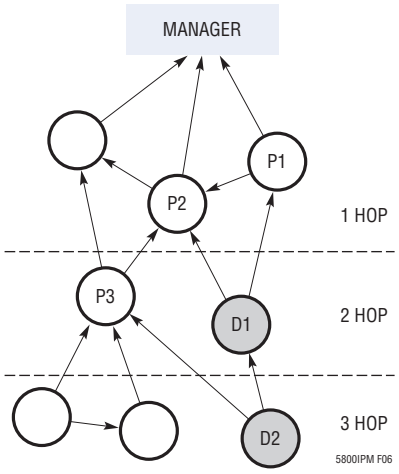


Figure 10. Example Network Graph

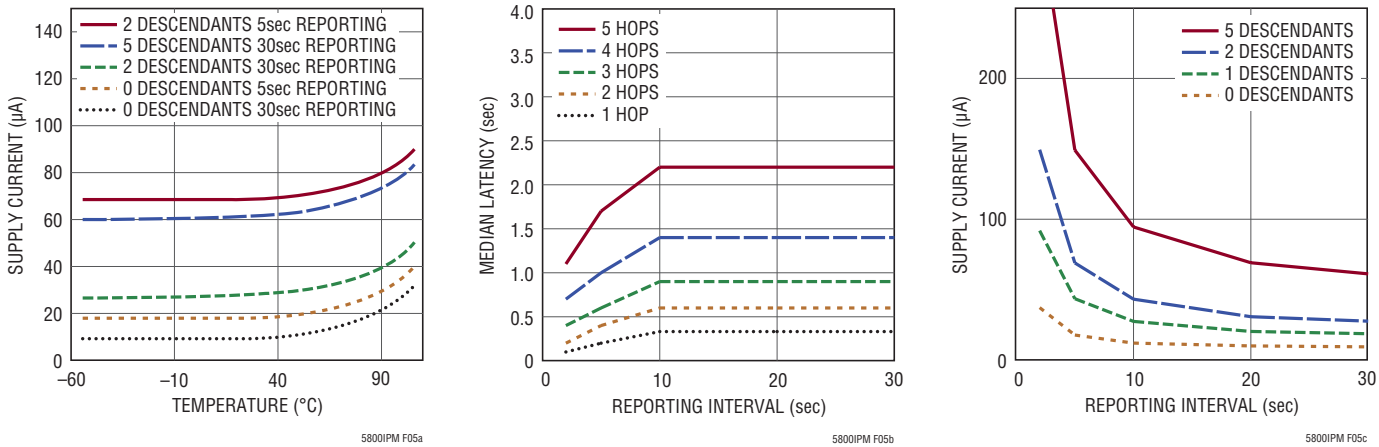
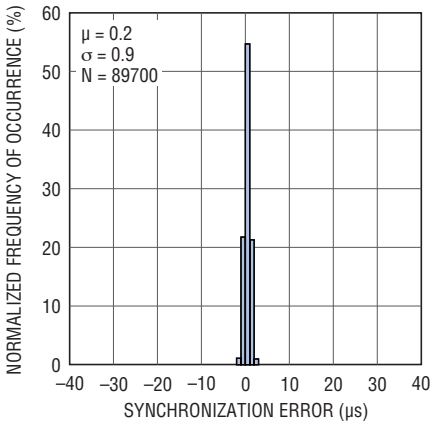


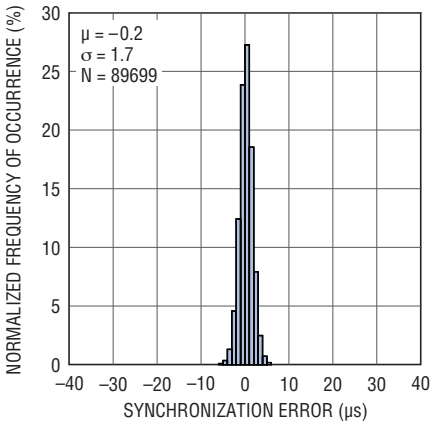
Figure 9

TYPICAL PERFORMANCE CHARACTERISTICS

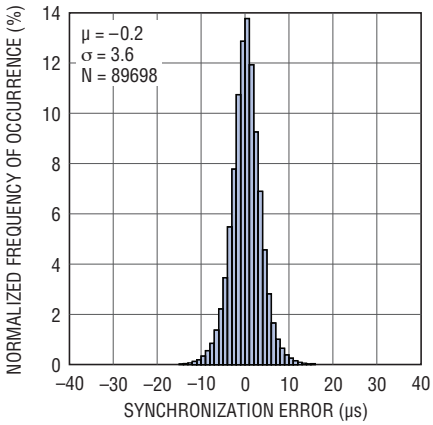
TIMEn Synchronization Error 0 Packet/s Publishing Rate, 1 Hop, Room Temperature



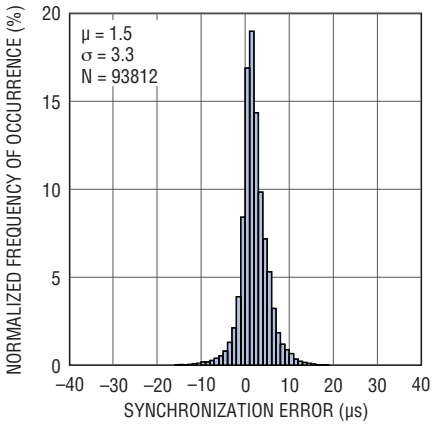
TIMEn Synchronization Error 0 Packet/s Publishing Rate, 3 Hops, Room Temperature



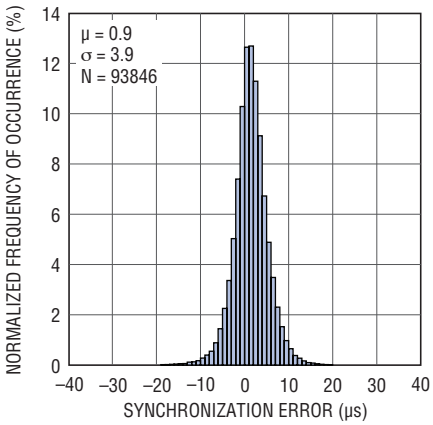
TIMEn Synchronization Error 0 Packet/s Publishing Rate, 5 Hops, Room Temperature



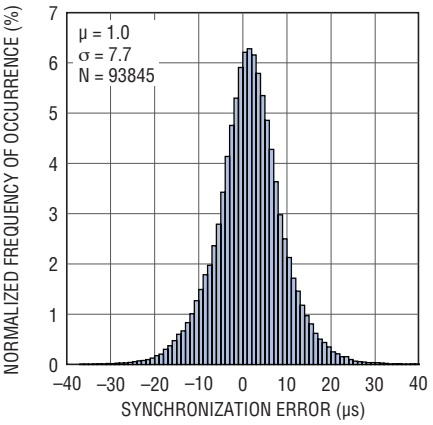
TIMEn Synchronization Error 0 Packet/s Publishing Rate, 1 Hop, 2°C/Min



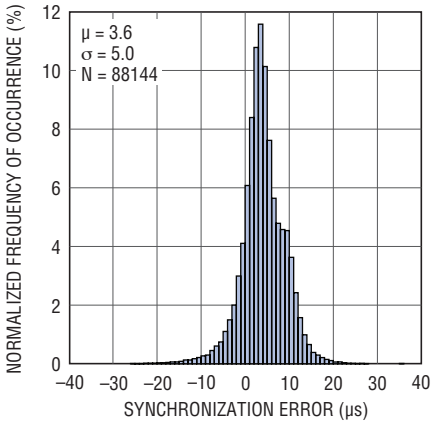
TIMEn Synchronization Error 0 Packet/s Publishing Rate, 3 Hops, 2°C/Min



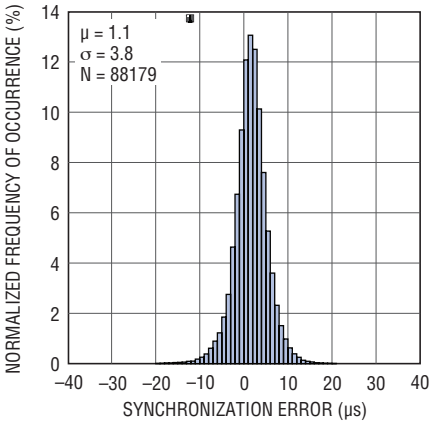
TIMEn Synchronization Error 0 Packet/s Publishing Rate, 5 Hops, 2°C/Min



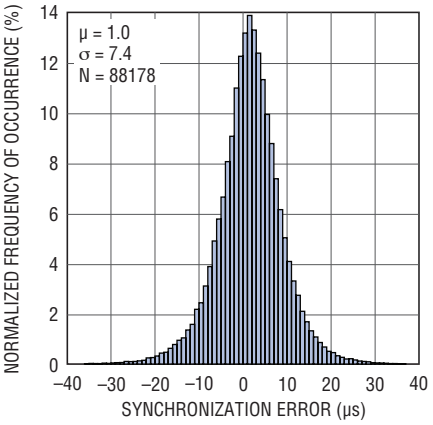
TIMEn Synchronization Error 0 Packet/s Publishing Rate, 1 Hop, 8°C/Min



TIMEn Synchronization Error 0 Packet/s Publishing Rate, 3 Hops, 8°C/Min

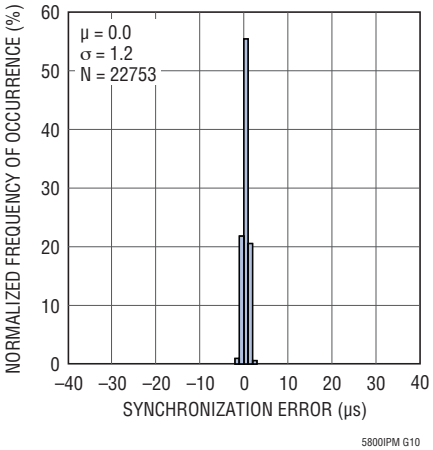


TIMEn Synchronization Error 0 Packet/s Publishing Rate, 5 Hops, 8°C/Min

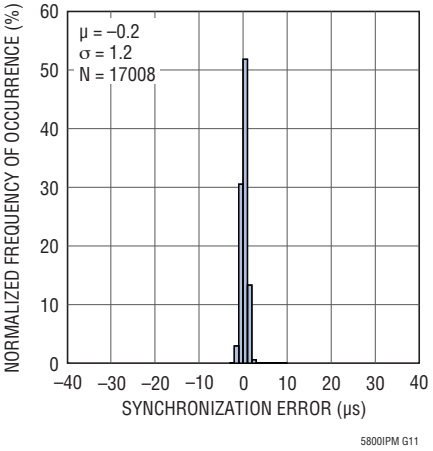


TYPICAL PERFORMANCE CHARACTERISTICS

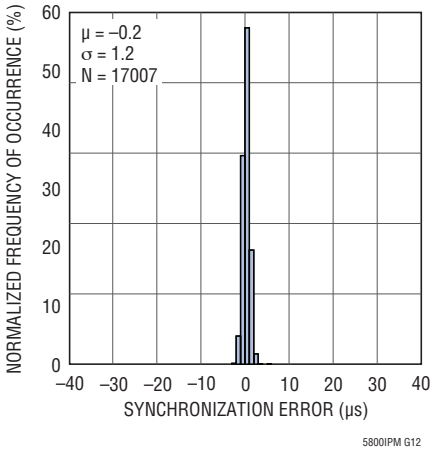
TIMEn Synchronization Error 1 Packet/s Publishing Rate, 1 Hop, Room Temperature



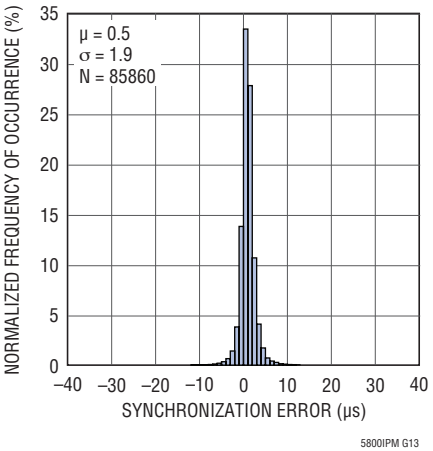
TIMEn Synchronization Error 1 Packet/s Publishing Rate, 3 Hops, Room Temperature



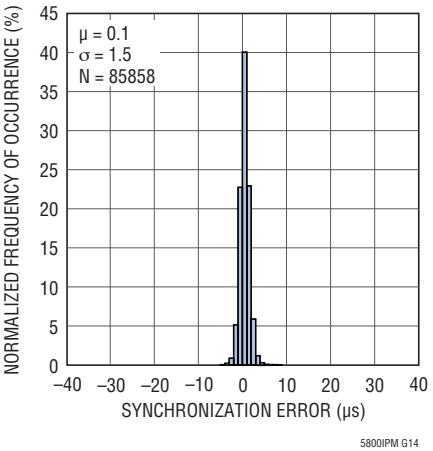
TIMEn Synchronization Error 1 Packet/s Publishing Rate, 5 Hops, Room Temperature



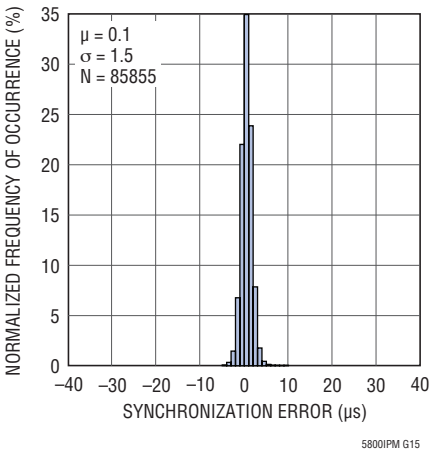
TIMEn Synchronization Error 1 Packet/s Publishing Rate, 1 Hop, 2°C/Min



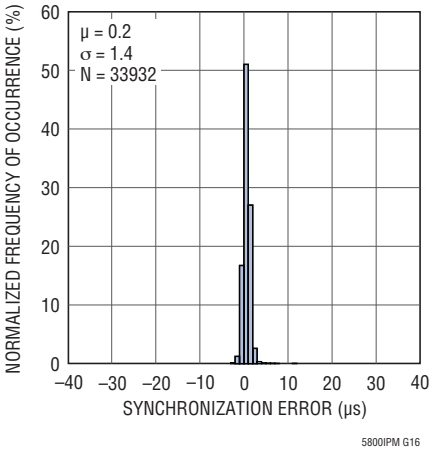
TIMEn Synchronization Error 1 Packet/s Publishing Rate, 3 Hops, 2°C/Min



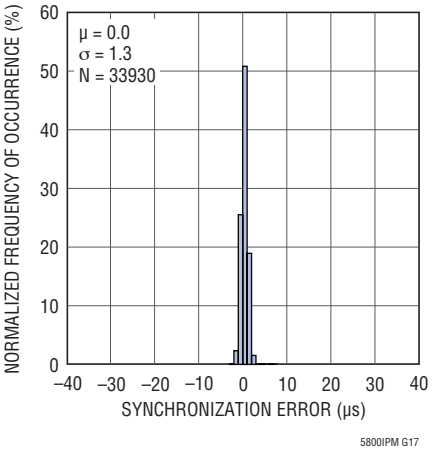
TIMEn Synchronization Error 1 Packet/s Publishing Rate, 5 Hops, 2°C/Min



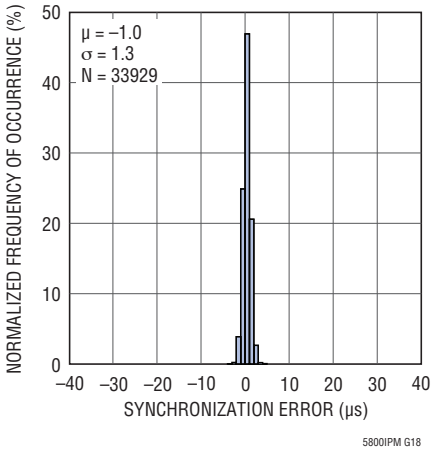
TIMEn Synchronization Error 1 Packet/s Publishing Rate, 1 Hop, 8°C/Min



TIMEn Synchronization Error 1 Packet/s Publishing Rate, 3 Hops, 8°C/Min



TIMEn Synchronization Error 1 Packet/s Publishing Rate, 5 Hops, 8°C/Min



TYPICAL PERFORMANCE CHARACTERISTICS

As described in the SmartMesh Network Overview section, devices in network spend the vast majority of their time inactive in their lowest power state (doze). On a synchronous schedule a mote will wake to communicate with another mote. Regularly occurring sequences which wake, perform a significant function and return to sleep are considered atomic. These operations are considered atomic as the sequence of events can not be separated into smaller events while performing a useful function. For example, transmission of a packet over the radio is an atomic operation. Atomic operations may be characterized in either charge or energy. In a time slot where a mote successfully sends a packet, an atomic transmit includes setup prior to sending the message, sending the message, receiving the acknowledgment and the post processing needed as a result of the message being sent. Similarly in a time slot when a mote successfully receives a packet, an atomic receive includes setup prior to listening, listening until the start of the packet transition, receiving the packet, sending the acknowledgement and post processing required due to the arrival of the packet.

To ensure reliability each mote in the network is provided multiple time slots for each packet it nominally will send and forward. The time slots are assigned to communicate upstream, toward the manager, with at least two different motes. When combined with frequency hopping this provides temporal, spatial and spectral redundancy. Given this approach a mote will often listen for a message that it will never receive, since the time slot is not being used by the transmitting mote. It has already successfully transmitted the packet. Since typically 3 time slots are scheduled for every 1 packet to be sent or forwarded, motes will perform more of these atomic “idle listens” than atomic transmit or atomic receive sequences. Examples of transmit, receive and idle listen atomic operations are shown in Figure 11.

TYPICAL PERFORMANCE CHARACTERISTICS

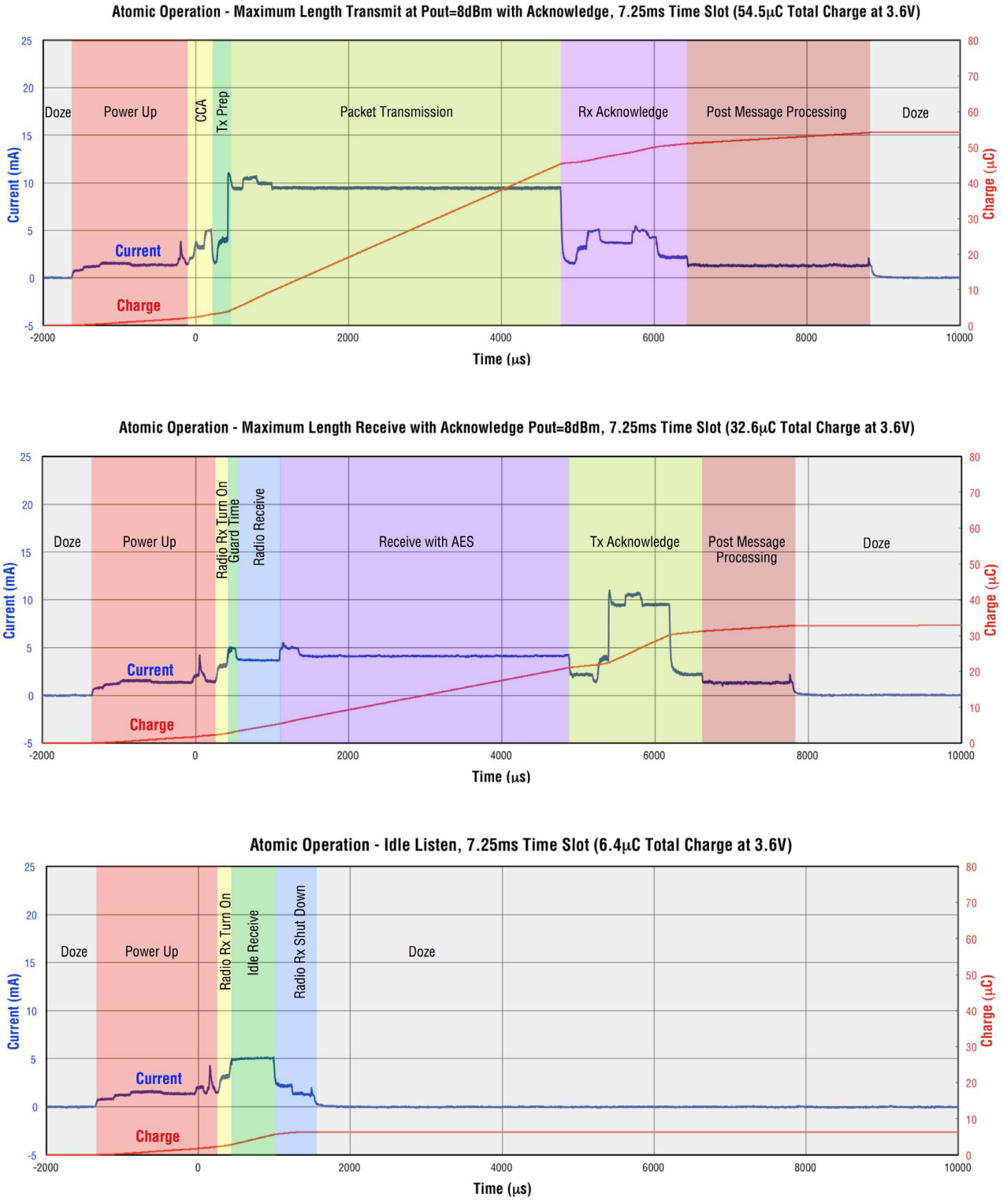


Figure 11

PIN FUNCTIONS

Pin functions shown in italics are currently not supported in software.

The following table organizes the pins by functional groups. For those I/O with multiple functions the alternate functions are shown on the second and third line in their respective row. The **No** column provides the pin number. The second column lists the function. The **Type** column lists the I/O type. The **I/O** column lists the direction of the signal relative to Eterna. The **Pull** column shows which signals have a fixed passive pull-up or pull-down. The **Description** column provides a brief signal description.

NO	POWER SUPPLY	TYPE	I/O	PULL	DESCRIPTION
P	GND	Power	-	-	Ground Connection, P = QFN Paddle
2	CAP_PA_1P	Power	-	-	PA DC/DC Converter Capacitor 1 Plus Terminal
3	CAP_PA_1M	Power	-	-	PA DC/DC Converter Capacitor 1 Minus Terminal
4	CAP_PA_2M	Power	-	-	PA DC/DC Converter Capacitor 2 Minus Terminal
5	CAP_PA_2P	Power	-	-	PA DC/DC Converter Capacitor 2 Plus Terminal
6	CAP_PA_3P	Power	-	-	PA DC/DC Converter Capacitor 3 Plus Terminal
7	CAP_PA_3M	Power	-	-	PA DC/DC Converter Capacitor 3 Minus Terminal
8	CAP_PA_4M	Power	-	-	PA DC/DC Converter Capacitor 4 Minus Terminal
9	CAP_PA_4P	Power	-	-	PA DC/DC Converter Capacitor 4 Plus Terminal
10	VDDPA	Power	-	-	Internal Power Amplifier Power Supply, Bypass
30	VDDA	Power	-	-	Regulated Analog Supply, Bypass
31	VCORE	Power	-	-	Regulated Core Supply, Bypass
32	VOSC	Power	-	-	Regulated Oscillator Supply, Bypass
54	VPP	Test			Internal Regulator Test Port
56	VPRIME	Power	-	-	Internal Primary Power Supply, Bypass
57	CAP_PRIME_4P	Power	-	-	Primary DC/DC Converter Capacitor 4 Plus Terminal
58	CAP_PRIME_4M	Power	-	-	Primary DC/DC Converter Capacitor 4 Minus Terminal
59	CAP_PRIME_3M	Power	-	-	Primary DC/DC Converter Capacitor 3 Minus Terminal
60	CAP_PRIME_3P	Power	-	-	Primary DC/DC Converter Capacitor 3 Plus Terminal
61	CAP_PRIME_2P	Power	-	-	Primary DC/DC Converter Capacitor 2 Plus Terminal
62	CAP_PRIME_2M	Power	-	-	Primary DC/DC Converter Capacitor 2 Minus Terminal
63	CAP_PRIME_1M	Power	-	-	Primary DC/DC Converter Capacitor 1 Minus Terminal
64	CAP_PRIME_1P	Power	-	-	Primary DC/DC Converter Capacitor 1 Plus Terminal
65	VSUPPLY	Power	-	-	Power Supply Input to Eterna

NO	RADIO	TYPE	I/O	PULL	DESCRIPTION
1	RADIO_INHIBIT	1 (Note 14)	I	-	Radio Inhibit
11	LNA_EN *GPIO17*	1	O *I/O*	- -	External LNA Enable *General Purpose Digital I/O*
12	RADIO_TX *GPIO18*	1	O *I/O*	- -	Radio TX Active (External PA Enable/Switch Control) *General Purpose Digital I/O*
13	RADIO_TXn *GPIO19*	1	O *I/O*	- -	Radio TX Active (External PA Enable/Switch Control), Active Low *General Purpose Digital I/O*
14	ANTENNA	-	-	-	Single-Ended Antenna Port, 50Ω

PIN FUNCTIONS

Pin functions shown in italics are currently not supported in software.

NO	ANALOG	TYPE	I/O	PULL	DESCRIPTION
15	AI_0	Analog	I	-	Analog Input 0
16	AI_1	Analog	I	-	Analog Input 1
17	AI_3	Analog	I	-	Analog Input 3
18	AI_2	Analog	I	-	Analog Input 2

NO	CRYSTALS	TYPE	I/O	PULL	DESCRIPTION
19	OSC_32K_XOUT	Crystal	I	-	32 kHz Crystal Xout
20	OSC_32K_XIN	Crystal	I	-	32 kHz Crystal Xin
28	OSC_20M_XIN	Crystal	I	-	20 MHz Crystal Xin
29	OSC_20M_XOUT	Crystal	I	-	20 MHz Crystal Xout

NO	RESET	TYPE	I/O	PULL	DESCRIPTION
22	RESETn	1	I	UP	Reset Input, Active Low

NO	JTAG	TYPE	I/O	PULL	DESCRIPTION
23	TDI	1	I	UP	JTAG Test Data In
24	TDO	1	O	-	JTAG Test Data Out
25	TMS	1	I	UP	JTAG Test Mode Select
26	TCK	1	I	DOWN	JTAG Test Clock

NO	GPIOS (NOTE 14)	TYPE	I/O	PULL	DESCRIPTION
27	DP4 (GPIO23)	1	I/O	-	General Purpose Digital I/O
33	DP3 (GPIO22) *TIMER8_EXT*	1	I/O I	- -	General Purpose Digital I/O *External Input to 8-Bit Timer/Counter*
34	DP2 (GPIO21) *LPTIMER_EXT*	1	I/O *I*	- -	General Purpose Digital I/O *External Input to Low Power Timer/Counter*
36	DP0 (GPIO0) SPIM_SS_2n	1	I/O O	- -	General Purpose Digital I/O SPI Master Slave Select 2, Active Low
48	DP1 (GPIO20) *TIMER16_EXT*	1	I/O *I*	- -	General purpose digital I/O *External Input to 16-Bit Timer/Counter*

NO	SPECIAL PURPOSE	TYPE	I/O	PULL	DESCRIPTION
35	*SLEEPn* *GPIO14*	1 (Note 14)	*I* *I/O*	- -	*Deep Sleep, Active Low* *General Purpose Digital I/O*
49	*PWM0* *TIMER16_OUT* GPIO16	2	*O* *O* I/O	- - -	*Pulse Width Modulator 0* *16-Bit Timer/Counter Match Output/PWM Output* General Purpose Digital I/O
72	TIMEn	1 (Note 14)	I	-	Time Capture Request, Active Low

NO	CLI	TYPE	I/O	PULL	DESCRIPTION
37	UARTC0_TX	2	O	-	CLI UART 0 Transmit
38	UARTC0_RX	1	I	UP	CLI UART 0 Receive

PIN FUNCTIONS

Pin functions shown in italics are currently not supported in software.

NO	SPI MASTER	TYPE	I/O	PULL	DESCRIPTION
39	SPIM_MISO GPIO11	1	I I/O	- -	SPI Master (MISO) Master In Slave Out Port General Purpose Digital I/O
41	SPIM_MOSI GPIO10	2	O I/O	- -	SPI Master (MOSI) Master Out Slave In Port General Purpose Digital I/O
43	SPIM_SCK GPIO9	2	O I/O	- -	SPI Master (SCK) Serial Clock Port General Purpose Digital I/O
46	SPIM_SS_1n GPIO13	1	O I/O	- -	SPI Master Slave Select 1, Active Low General Purpose Digital I/O
47	SPIM_SS_0n GPIO12	1	O I/O	- -	SPI Master Slave Select 0, Active Low General Purpose Digital I/O

NO	IPCS SPI/FLASH PROGRAMMING (NOTE 16)	TYPE	I/O	PULL	DESCRIPTION
40	IPCS_MISO *TIMER16_OUT* GPIO6	2	O O I/O	- - -	SPI Flash Emulation (MISO) Master In Slave Out Port *16-Bit Timer/Counter Match Output/PWM Output* General Purpose Digital I/O
42	IPCS_MOSI *TIMER16_EXT* GPIO5	1	I *I* I/O	- - -	SPI Flash Emulation (MOSI) Master Out Slave In Port *External Input to 16-bit Timer/Counter* General Purpose Digital I/O
44	IPCS_SCK *TIMER8_EXT* GPIO4	1	I *I* I/O	- - -	SPI Flash Emulation (SCK) Serial Clock Port *External Input to 8-Bit Timer/Counter* General Purpose Digital I/O
45	IPCS_SSn *LPTIMER_EXT* GPIO3	1	I *I* I/O	- - -	SPI Flash Emulation Slave Select, Active Low *External Input to Low Power Timer/Counter* General Purpose Digital I/O
55	FLASH_P_ENn	1	I	UP	Flash Program Enable, Active Low

NO	I^2C/1-WIRE/SPI SLAVE	TYPE	I/O	PULL	DESCRIPTION
50	*SPIS_MISO* *UARTC1_TX* 1_WIRE	2	*O* *O* I/O	- - -	*SPI Slave (MISO) Master In Slave Out Port* *CLI UART 1 Transmit* 1 Wire Master
51	*SPIS_MOSI* *UARTC1_RX* GPIO26	1	*I* *I* I/O	- - -	*SPI Slave (MOSI) Master Out Slave In Port* *CLI UART 1 Receive* General Purpose Digital I/O
52	*SPIS_SCK* SCL	2	*I* I/O	- -	*SPI Slave (SCK) Serial Clock Port* I2C Serial Clock
53	*SPIS_SSn* SDA	2	*I* I/O	- -	*SPI Slave Select, Active Low* I2C Serial Data

NO	API UART	TYPE	I/O	PULL	DESCRIPTION
66	UART_RX_RTSn	1 (Note 14)	I	-	UART Receive (RTS) Request to Send, Active Low
67	UART_RX_CTSn	1	O	-	UART Receive (CTS) Clear to Send, Active Low
68	UART_RX	1 (Note 14)	I	-	UART Receive
69	UART_TX_RTSn	1	O	-	UART Transmit (RTS) Request to Send, Active Low
70	UART_TX_CTSn	1 (Note 14)	I	-	UART Transmit (CTS) Clear to Send, Active Low
71	UART_TX	2	O	-	UART Transmit

Note 14: These inputs are always enabled and must be driven or pulled to a valid state to avoid leakage.

Note 15: See also pins 40, 42, 44, and 45 for additional GPIO ports.

Note 16: Embedded programming over the IPCS SPI bus is only avaliable when RESETn is asserted.

PIN FUNCTIONS

VSUPPLY: System and I/O Power Supply. Provides power to the chip including the on-chip DC/DC converters. The digital-interface I/O voltages are also set by this voltage. Bypass with 2.2µF and 0.1µF to ensure the DC/DC converters operate properly.

VDDPA: PA-Converter Bypass Pin. A 0.47µF cap should be connected from VDDPA to ground with as short a trace as feasible. Do not connect anything else to this pin.

VDDA: Analog-Regulator Bypass Pin. A 0.1µF cap should be connected from VDDA to ground with as short a trace as feasible. Do not connect anything else to this pin.

VCORE: Core-Regulator Bypass Pin. A 56nF cap should be connected from VCORE to ground with as short a trace as feasible. Do not connect anything else to this pin.

VOSC: Oscillator-Regulator Bypass Pin. A 56nF cap should be connected from VOSC to ground with as short a trace as feasible. Do not connect anything else to this pin.

VPP: Maunufacturing Test port for internal regulator. Do not connect anything to this pin.

VPRIME: Primary-Converter Bypass Pin. A 0.22µF cap should be connected from VPRIME to ground with as short a trace as feasible. Do not connect anything else to this pin.

VBGAP: Bandgap Reference Output. Used for testing and calibration. Do not connect anything to this pin.

CAP_PA_1P, CAP_PA_1M through CAP_PA_4P, CAP_PA_4M: Dedicated Power-Amplifier DC/DC Converter Capacitor Pins. These pins are used when the radio is transmitting to efficiently convert VSUPPLY to the proper voltage for the power amplifier. A 56nF cap should be connected between each P and M pair. Trace length should be as short as feasible.

CAP_PRIME_1P, CAP_PRIME_1M through CAP_PRIME_4P, CAP_PRIME_4M: Primary DC/DC Converter Capacitor Pins. These pins are used when the device is awake to efficiently convert VSUPPLY to the proper voltage for the three on-chip low-dropout regulators. A 56nF cap should be connected between each P and M pair. Trace length should be as short as feasible.

RADIO_INHIBIT: RADIO_INHIBIT provides a mechanism for an external device to temporarily disable radio operation. Failure to observe the timing requirements defined in the Radio_Inhibit AC Characteristics table, may result in unreliable network operation. In designs where the RADIO_INHIBIT function is not needed the input must either be tied, pulled or actively driven low to avoid excess leakage.

LNA_ENABLE, RADIO_TX, RADIO_TXn: Control signals generated by the autonomous MAC supporting the integration of an external LNA/PA. See the Eterna Extended Range Reference Design for implementation details.

ANTENNA: Multiplexed Receiver Input and Transmitter Output Pin. The impedance presented to the antenna pin should be 50Ω, single-ended with respect to paddle ground. To ensure regulatory compliance of the final product please see the Eterna Integration Guide for filtering requirements. The antenna pin should not have a DC path to ground; AC blocking must be included if a DC-grounded antenna is used.

AI_0, AI_1, AI_2, AI_3: Analog Inputs. These pins are multiplexed to the analog input chain. The analog input chain, as shown in Figure 12, is software-configurable and includes a variable-gain amplifier, an offset-DAC for adjusting input range, and a 10b ADC. Valid input range is between 0 to 1.8V. Analog inputs can be sampled as described in the On-Chip Software Development Kit (On-Chip SDK).

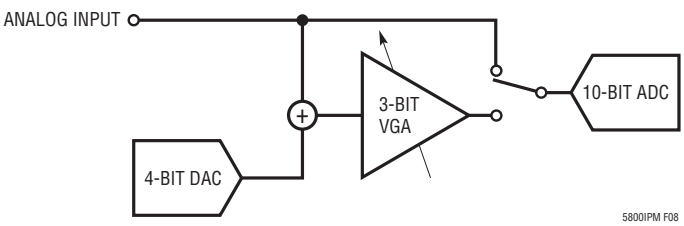


Figure 12. Analog Input Chain

PIN FUNCTIONS

OSC_32K_XOUT: Output Pin for the 32kHz Oscillator. Connect to 32kHz quartz crystal. The OSC_32K_XOUT and OSC_32K_XIN traces must be well-shielded from other signals, both on the same PCB layer and lower PCB layers, as shown in Figure 13.

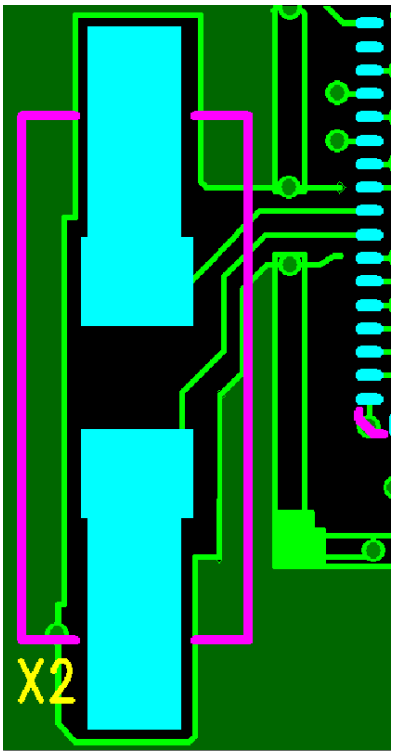


Figure 13. PCB Top Metal Layer Shielding of Crystal Signals

OSC_32K_XIN: Input for the 32kHz Oscillator. Connect to 32kHz quartz crystal.The OSC_32K_XOUT and OSC_32K_XIN traces must be well-shielded from other signals, both on the same PCB layer and lower PCB layers, as shown in Figure 13.

OSC_20M_XOUT: Output for the 20MHz Oscillator. Connect only to a supported 20MHz quartz crystal. The OSC_20M_XOUT and OSC_20M_XIN traces must be well-shielded from other signals, as shown in Figure 13. See the Eterna Integration Guide for supported crystals.

OSC_20M_XIN: Input for the 20MHz Oscillator. Connect only to a supported 20MHz quartz crystal. The OSC_20M_XOUT and OSC_20M_XIN traces must be well-shielded from other signals, both on the same PCB layer and lower PCB layers, as shown in Figure 13.

RESETn: The asynchronous reset signal is internally pulled up. Resetting Eterna will result in the ARM Cortex M3 rebooting and loss of network connectivity. Use of this signal for resetting Eterna is not recommended except during power-on and in-circuit programming.

TMS, TCK, TDI, TDO: JTAG Port Supporting Software Debug and Boundary Scan. An IEEE Std 1149.1b-1994 compliant Boundary Scan Definition Language (BDSL) file for the WR QFN72 package can be found here.

SLEEPn: The SLEEPn function is not currently supported in software. The SLEEPn input must either be tied, pulled or actively driven high to avoid excess leakage.

UART_RX, UART_RX_RTSn, UART_RX_CTSn, UART_TX, UART_TX_RTSn, UART_TX_CTSn: The API UART interface includes bi-directional wake up and flow control. Unused input signals must be driven or pulled to their inactive state.

TIMEn: Strobing the TIMEn input is the most accurate method to acquire the network time maintained by Eterna. Eterna latches the network timestamp with sub-microsecond resolution on the rising edge of the TIMEn signal and produces a packet on the API serial port containing the timing information.

UARTC0_RX, UARTC0_TX: The CLI UART provides a mechanism for monitoring, configuration and control of Eterna during operation. For a complete description of the supported commands see the SmartMesh IP Mote CLI Guide.

GPIO0, GPIO3 - GPIO6, GPIO9 - GPIO13, GPIO16, GPIO20 - GPIO23, GPIO26: General purpose IO that can be sampled or driven as described in the On-Chip Software Development Kit (On-Chip SDK).

PIN FUNCTIONS

FLASH_P_ENn, IPCS_SSn, IPCS_SCK, IPCS_MISO, IPCS_SSn: The In-circuit Programming Control System (IPCS) bus enables in-circuit programming of Eterna's flash memory. IPCS_SCK is a clock and should be terminated appropriately for the driving source to prevent overshoot and ringing.

SPIM_CLK, SPIM_MISO, SPIM_MOSI, SPIM_SS_0n, SPIM_SS_1n, SPIM_SS_4n: The SPI Master bus with support for up to three SPI slave devices, via the On-Chip Software Development Kit (On-Chip SDK) provides an interface to SPI peripheral slave devices. The SPI interface is syncrhonous to SPIM_CLK, which should be treated as a clock singal and terminated appropriately .

1_WIRE: The 1-Wire master clock/data/power signal. See the On-Chip Software Development Kit (On-Chip SDK) for details on operating the 1-Wire Master controller.

SCL, SDA: The I^2C bus SCL and SDA should be externally pulled to VSUPPLY with a 10kΩ resistor. See the On-Chip Software Development Kit (On-Chip SDK) for details on operating the 1-Wire Master controller.